

EDIT HISTORY

Version A : Apr. 18, 2014

Preliminary Spec.

Manufacture	Examination	Approving		
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FEATURES

- 0.56 inch (14.20 mm) Digit Height.
- Excellent character appearance.
- Case mold type.
- Low Power Consumption.
- Gray face, White segment.
- RoHS compliant, Pb Free.

DESCRIPTION

The A561E G/W & C561E G/W is a 0.56 inch (14.20 mm) height single 7-segment display. This device utilizes High Effcency Red LED chip which are made from GaAsP on a transparent GaP substrate. The display has Gray face, White segment.

DEVICE

PART NO High Effcency Red	DESCRIPTION		
A561E G/W	Common Anode		
C561E G/W	Common Cathode		

RoHS Compliance



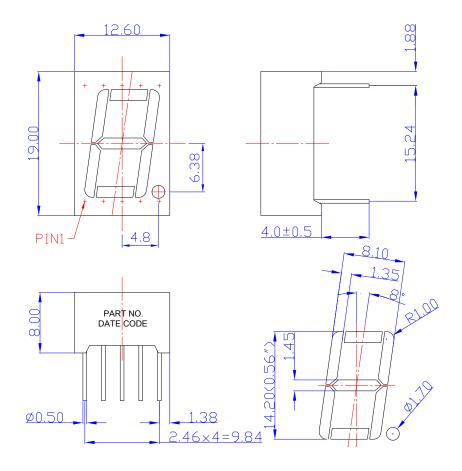
Pb free.



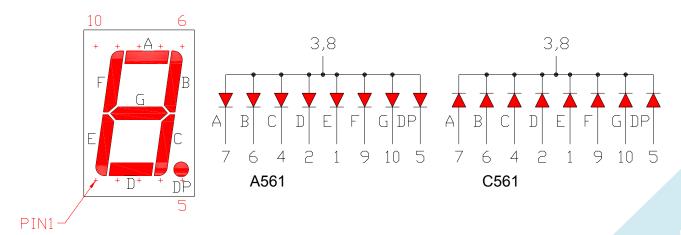
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MECHANICAL DIMENSIONS



TYPICAL INTERNAL EQUIVALENT CIRCUIT





E: RED (GaAsP/GaP)

ABSOLUTE MAXIMUM RATING AT Ta=25°C

Parameter	Symbol	Red	Unit
Power dissipation per dice	P _{AD}	70	mW
Derating Liner from 25°C per dice	-	0.33	mA/°C
Continuous forward current per dice	I _{AF}	25	mA
Peak current per dice (duty cycle 1/10, 1kHz)	I _{PF}	90	mA
Reverse voltage per dice	V_R	5	V
Operating temperature	T _{OPR}	-25 to +85	°C
Storage temperature	T _{STG}	-25 to +85	°C

ELECTRICAL - OPTICAL CHARACTERISTICS AT Ta=25°C

Characteristic	Symbol	Condition	Min.	Туре	Max.	Unit
Forward voltage	V _F	I _F =20mA	-	2.0	2.6	V
Reverse current	I _R	V _R =5V	-	-	10	μA
Peak wavelength	λР	I _F =20mA	-	632	-	nm
Dominant wavelength	$\lambda_{\sf d}$	I _F =20mA	-	620	-	nm
Luminous intensity	I _V	I _F =20mA	-	10	-	mcd
Spectral radiation bandwidth	Δλ	I _F =20mA	-	35	-	nm



● E: RED (GaAsP/GaP) CURVE

Typical Electro-optical Characteristic Curves (25 °C Free Air Temperature Unless Otherwise Specified)

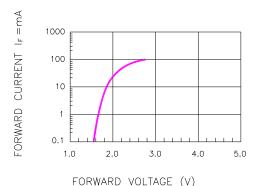
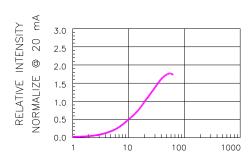


Fig.1 FORWARD CURRENT VS. FORWARD VOLTAGE



FORWARD CURRENT (mA)
Fig.2 RELATIVE INTENSITY VS. FORWARD CURRENT

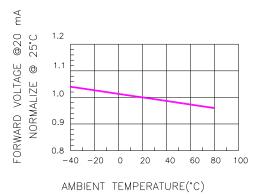


Fig.3 FORWARD VOLTAGE VS. TEMPERATURE

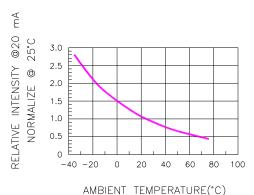


Fig.4 RELATIVE INTENSITY VS. TEMPERATURE

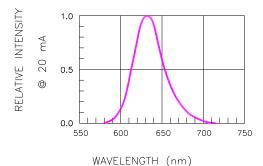
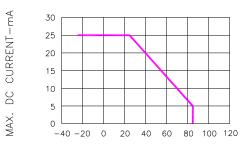


Fig.5 RELATIVE INTENSITY VS. WAVELENGTH

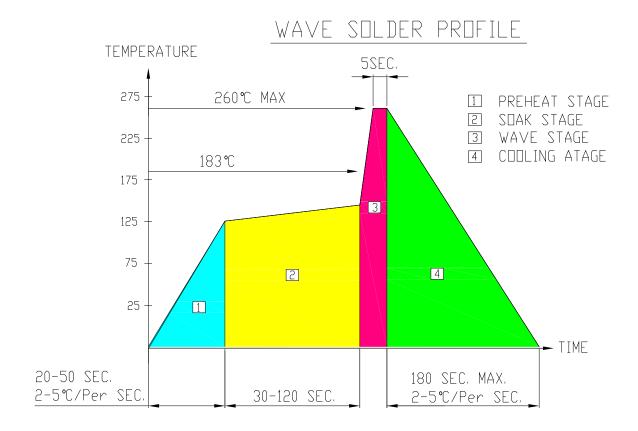


AMBIENT TEMPERATURE (TA)-°C

Fig.6 MAX. ALLOWABLE DC CURRENT VS. AMBIENT TEMPERATURE



RECOMMEND SOLDERING PROFILE



SOLDERING IRON

Basic spec is ≦4 sec when 260°C. If temperature is higher, time should be shorter (+10°C→1 sec). Power dissipation of Iron should be smaller than 15W, and temperature should be controllable. Surface temperature of the device should be under 230°C.

REWORK

Customer must finish rework within ≦4 sec under 245°C.

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